

TAIWAN SEMICONDUCTOR MANUFACTURING CO LTD

Form 6-K

August 14, 2007

1934 Act Registration No. 1-14700

**SECURITIES AND EXCHANGE COMMISSION**  
**Washington, DC 20549**  
**FORM 6-K**  
**REPORT OF FOREIGN PRIVATE ISSUER**  
**PURSUANT TO RULE 13a-16 OR 15d-16 OF**  
**THE SECURITIES EXCHANGE ACT OF 1934**  
**For the month of August 2007**  
**Taiwan Semiconductor Manufacturing Company Ltd.**  
(Translation of Registrant's Name Into English)  
**No. 8, Li-Hsin Rd. 6,**  
**Hsinchu Science Park,**  
**Taiwan**  
(Address of Principal Executive Offices)

(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F  Form 40-F

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes  No

(If Yes is marked, indicated below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82: \_\_\_\_\_.)

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**TSMC Board of Directors Approves First-Half Financial Statements**

**Hsinchu, Taiwan, R.O.C., August 14, 2007** TSMC held a meeting of the Board of Directors today, at which the Board approved financial statements for the first half of 2007. Consolidated revenue for the first six months of 2007 totaled NT\$139,815 million, while consolidated net income was NT\$44,323 million.

TSMC Spokesperson and Vice President Ms. Lora Ho said other major conclusions of the Board meeting were as follows:

1. Approved capital appropriations totaling US\$59.8 million for establishing 12-inch wafer level packaging technology and capacity to meet future market demand. Wafer level packaging technology can effectively reduce the size of end-products and raise the competitiveness of TSMC and its customers.
2. Approved capital appropriations totaling US\$22.8 million for upgrading a monthly capacity of 12,600 eight-inch wafers in 0.18 micron logic process to 11,100 eight-inch wafers capable of high voltage, radio frequency (RF), and BiCMOS processes.

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**For further information, please contact:**

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**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Taiwan Semiconductor Manufacturing Company Ltd.

Date: August 14, 2007

By /s/ Lora Ho  
Lora Ho  
Vice President & Chief Financial Officer